PRODUCT CHANGE NOTICE				
PART NUMBER(S):	PCN No.: 06-0130-26			
Please see attachment.	DATE: January 30, 2006			
PART DESCRIPTION:				
Power Management and Interface Products – Change in Wafer Fabrication Site				
LEVEL OF CHANGE:				
[X] Level I, Customer Approval.	[ ] Level II, Customer Information.			
PRODUCT ATTRIBUTE AFFECTED:				
<ul><li>[ ] Material Change</li><li>[ ] Design Change</li><li>[X] Process Change</li><li>[X] Other, Explain: Wafer Fabrication</li></ul>	[ ] Data Sheet Change [ ] Package Change [ ] Packing / Shipping Site Transfer			
DESCRIPTION OF CHANGE:				
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Silan. See attached Product List no. 26.				
REASON FOR CHANGE:				
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.				
	RODUCT CHARACTERIZATION COMPLETED AND AMPLES* AVAILABLE (DATE): June 22, 2006			

<sup>\*</sup> Samples representative of product from the Product Family being transferred.



PRODUCT CHANGE NOTICE				
EARLIEST DATE OF PRODUC SHIPMENTS: November 16, 20	006			
EFFECTIVITY CHANGE DATE	OR DATE CODE: Work w	eek associated w	th earliest production shipment.	
[ ] STANDARD DISTRIBUTI	ON	[X]	CUSTOM DISTRIBUTION	
PERSON TO CONTACT WITH	QUESTIONS:			
Fred Claussen				
VP Quality Assurance and Relia Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	ability			



## PRODUCT CHANGE NOTICE

PCN No.: 06-0130-26

List 26

SP504CF SP504CF-L SP504MCF SP504MCF-L SP514CF SP514CF-L